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Electronic Patent Application Submission
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EFS ID: 24716
Application ID: 09687048
Title of Invention: LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH
First Named Inventor: Kuri-Shi Lee
Domestic/Foreign Application: Domestic Application
Filing Date: 2000-10-13
Effective Receipt Date: 2003-03-17
Submission Type: Information Disclosure Statement
Filing Type: null
Confirmation Number: 1120
Attorney Docket Number: AMKOR-052A
Digital Certificate Holder: cn=Mark B. Garred, ou=Registered Attorneys, ou=Patent and Trademark Office, ou=Department of Commerce, o=U.S. Government, c=US
Certificate Message Digest: ZXgkwJatUUiy2aFpbvfxuQ==



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Electronic Version 1.0.3

Stylesheet Version: 1.0

Submission Type: Information
Disclosure Statement

Application Number: 09/687,048
Attorney Docket Number: AMKOR-052A

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

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Comments:

Electronic Information Disclosure Statement



LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

Application:



09/687048

Confirmation: 1120

Applicant(s): Kuri-Shi Lee

Docket

AMKOR-052A

Number:

Group Art

2814

Unit:

Examiner: Dilinh P. Nguyen

(6075284 or 6072228 or 6060769 or 6060768 or 6043430 or 6040626 or 6034423 or 6031279 or 6025640 or 6018189 or 6013947 or 6001671 or 5986885 or 5986333 or 5981314 or 5977615 or 5976912 or 5973388 or 5959356 or 5951305 or 5942794 or 5939779 or 5917242 or 5903050 or 5903049 or 5900676 or 5897339 or 5886398 or 5877043 or 5874784 or 5859471 or 5844306 or 5834830 or 5821615 or 5821457 or 5818105 or 5817540 or 5814884 or 5814883 or 5814881 or 5814877 or 5801440 or 5776798 or 5770888 or 5766972 or 5753977 or 5745984 or 5736432 or 5723899 or 5710064).pn.

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US Patent Documents